

# MA22D15

## Silicon epitaxial planar type

For high frequency rectification

### ■ Features

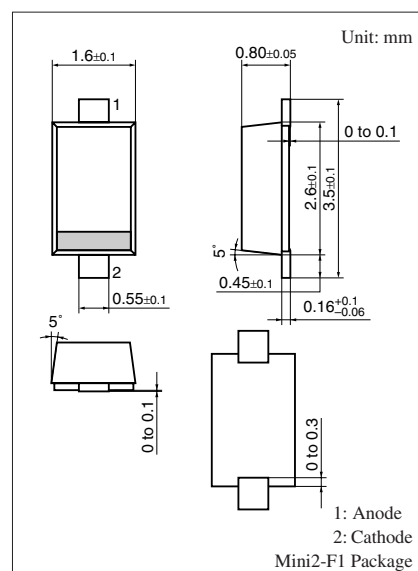
- $I_{F(AV)} = 1$  A rectification is possible
- Low forward voltage  $V_F$
- Low reverse current  $I_R$

### ■ Absolute Maximum Ratings $T_a = 25^\circ\text{C}$

Parameter	Symbol	Rating	Unit
Reverse voltage	$V_R$	20	V
Repetitive peak reverse voltage	$V_{RRM}$	25	V
Forward current (Average) *1	$I_{F(AV)}$	1.0	A
Non-repetitive peak forward surge current *2	$I_{FSM}$	20	A
Junction temperature	$T_j$	150	$^\circ\text{C}$
Storage temperature	$T_{stg}$	-55 to +150	$^\circ\text{C}$

Note) \*1: Mounted on a alumina PC board

\*2: The peak-to-peak value in one cycle of 50 Hz sine wave (non-repetitive)



Marking Symbol: 3R

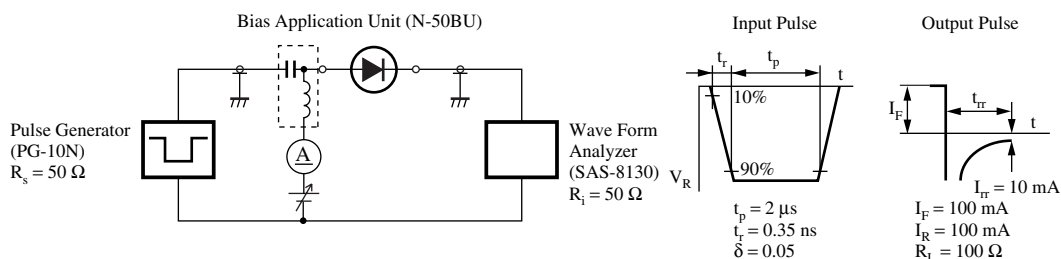
### ■ Electrical Characteristics $T_a = 25^\circ\text{C} \pm 3^\circ\text{C}$

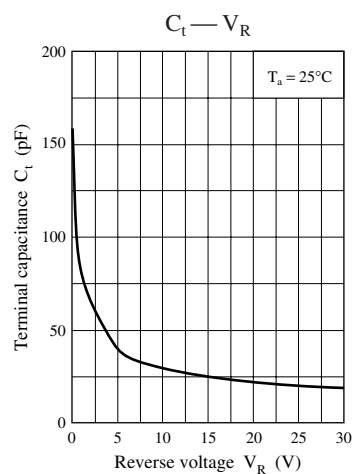
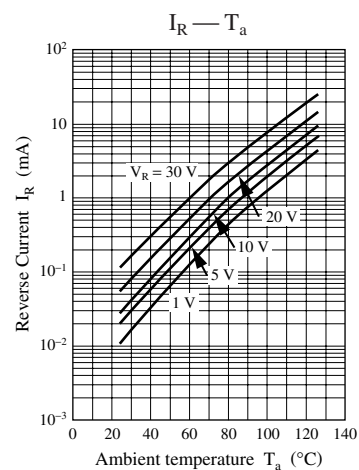
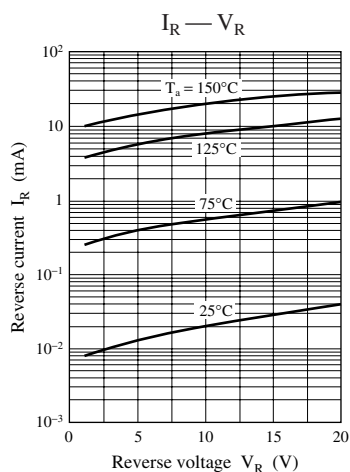
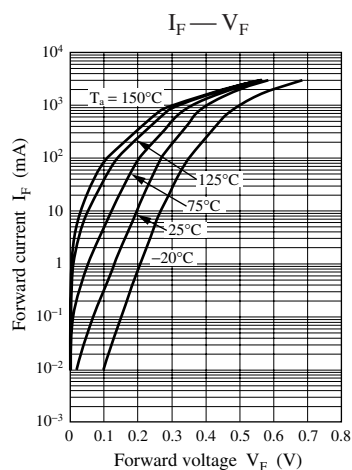
Parameter	Symbol	Conditions	Min	Typ	Max	Unit
Forward voltage	$V_F$	$I_F = 1.0$ mA		0.40	0.43	V
Reverse current	$I_R$	$V_R = 20$ V			100	$\mu\text{A}$
Terminal capacitance	$C_t$	$V_R = 10$ V, $f = 1$ MHz		30		pF
Reverse recovery time *	$t_{rr}$	$I_F = I_R = 100$ mA $I_R = 10$ mA, $R_L = 100 \Omega$		10		ns

Note) 1. Measuring methods are based on JAPANESE INDUSTRIAL STANDARD JIS C 7031 measuring methods for diodes.

2. This product is sensitive to electric shock (static electricity, etc.). Due attention must be paid on the charge of a human body and the leakage of current from the operating equipment.

3. \*:  $t_{rr}$  measuring instrument





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